PCN Number: 20230515000.2							Ρ	CN Date:	May 17, 2023		
Title:	Qualifica	ation of	of new BOM for select package Devices								
Custon	er Contact	:: <u>P</u>	CN Manage	<u>Dept</u> :		Quality Se	ervice	vices			
Proposed 1 st Ship Date			Nov 16,	2023	Sample requests accepted until:			June 16, 2023*			
*Sample requests received after June 16, 2023 will not be supported.											
Change Type:											
As	sembly Site				Design			Wafer Bump Site			
	sembly Proc			Data	Data Sheet			Wafer Bump Material			
	sembly Mat		P		Part number change			Wafer Bump Process			
	chanical Sp				Test Site			Wafer Fab Site			
L Pa	cking/Shipp	ing/Lat	beling	L Test	Test Process		Ш	Wafer Fab Materials			
								Wafer Fab Process			
PCN Details											
Descrip	tion of Ch	ange:									
Texas Instruments Incorporated is announcing the qualification of new material set for the devices listed in the "Product Affected" Section. Devices will remain at current location. Material Difference:											
			Current		Propos	ed					
Lea	d finish		NiPdAu		Matte Sn						
 Upon expiration of this PCN, TI will combine lead free solutions in a single <u>standard part</u> <u>number</u>, for example; <u>TL331IDBVR</u> - can ship with both Matte Sn and NiPdAu. Example: Customer order for 7500 units of SN566230RJER with 2500 units SPQ (Standard Pack Quantity per Reel). TI can satisfy the above order in one of the following ways. I. 3 Reels of NiPdAu finish. II. 3 Reels of Matte Sn finish III. 2 Reels of Matte Sn and 1 reel of NiPdAu finish. IV. 2 Reels of NiPdAu and 1 reel of Matte Sn finish. 											
Reason for Change:											
Continuity of supply.											
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):											
None											
Impact on Environmental Ratings											
Checked boxes indicate the status of environmental ratings following implementation of this											
change. If below boxes are checked, there are no changes to the associated environmental ratings.											
	RoHS		R	EACH		Green Stat	us	IEC	C 62474		
No No	Change		No Cha	-		lo Change	-	No Cl			

Changes to product identification resulting from this PCN:							
Sample product shipping TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL '2 /260C/1 YEAR SEAL MSL 1 /235C/UNLIM 03/28 OPT: ITEM: 39 LBL: 5A (L)T0:17	G4 DT 0/04	Ct label) G4 = NiPdAu G3 = Matte Sn (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CC0:USA (22L) AS0: MLA (23L) AC0: MYS					
Product Affected:							
TL331IDBVR	TL331IDBVT	TL331KDBVR					

Qualification Report Approve Date 03-Apr- 2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>TPS76933DBVR</u>	Qual Device: TL331IDBVRG4	Qual Device: <u>TLV9051SIDBVR</u>	Qual Device: TPS2553DDBVR	Qual Device: <u>LV3842XDBVR</u>	QBS Reference: <u>TLV9061IDBVR</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0
тс	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0	-	3/231/0
тс	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	3/231/0
HTOL	В1	Life Test	150C	300 Hours	-	-	-	-	-	3/231/0
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	-	-	-	3/228/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	-	-	3/228/0
SD	СЗ	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	1/22/0	1/22/0	1/22/0	1/22/0	1/22/0	3/66/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	-	-	3/15/0
FTY	E6	Final Test Yield	-	-	-	-	-	-	-	3/3/0

QBS: Qual By Similarity

Qual Device TPS76933DBVR is qualified at MSL1 260C

Qual Device TL3311DBVRG4 is qualified at MSL1 260C Qual Device TLV9051SIDBVR is qualified at MSL1 260C Qual Device TPS2553DDBVR is qualified at MSL1 260C Qual Device LV3842XDBVR is qualified at MSL1 260C Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

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Location	E-Mail				
WW Change Management Team	PCN ww admin team@list.ti.com				

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